

AMPMODU | AMPMODU Headers

TE Internal #: 1-103542-9 PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Press-Fit, AMPMODU Headers

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **40**

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Unshrouded

Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	40
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Body Features	
Primary Product Color	Black
Contact Features	
	100 – 200 µin

PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Press-Fit, AMPMODU Headers



Contact Underplating MaterialNickelPCB Contact Termination Area Plating MaterialTin-LeadContact Base MaterialCopper AlloyContact Mating Area Plating Material ThicknessGoldContact TypePinContact Current Rating (Max)3 A
Contact Base MaterialCopper AlloyContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 μm[30 μin]Contact TypePin
Contact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 µm[30 µin]Contact TypePin
Contact Mating Area Plating Material Thickness .76 µm[30 µin] Contact Type Pin
Contact Type Pin
Contact Current Rating (Max) 3 A
Termination Features
Termination Post & Tail Length 6.35 mm[.25 in]
Termination Method to Printed Circuit Board Through Hole - Press-Fit
Mechanical Attachment
PCB Mount Retention Type Action/Compliant Tail
Mating Alignment Without
PCB Mount Retention With
PCB Mount Alignment Without
Connector Mounting Type Board Mount

Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-55 – 125 °C[-67 – 257 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Rating	Recognized
Agency/Standard	CSA, UL
Approved Standards	CSA LR16455, UL E28476

C For support call+1 800 522 6752

PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Press-Fit, AMPMODU Headers



UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Carton
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Not Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) SVHC > Threshold: Pb (40% in component) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Not Yet Reviewed for halogen content
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Press-Fit, AMPMODU Headers



Also in the Series AMPMODU Headers









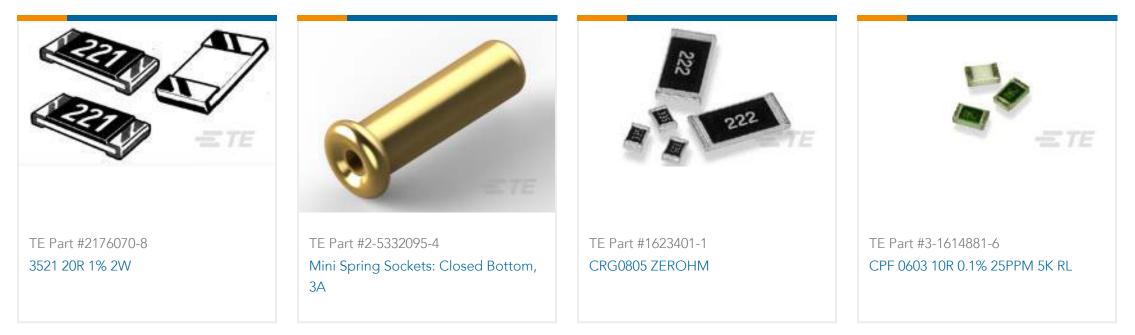
PCB Connector Mounting(1)

PCB Connector Shrouds(1)

PCB Headers & Receptacles(4875) PCB Latches, Locks & Retainers(1)

 Wire-to-Board Connector Assemblies & Housings(5)
 Wire-to-Board Connector Contacts(65)

Customers Also Bought





Documents

Product Drawings 40 MODII HDR DRST UNSHRD A/PIN

English

CAD Files

3D PDF

English

S For support call+1 800 522 6752

PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Press-Fit, AMPMODU Headers



Customer View Model

ENG_CVM_1-103542-9_J.3d_igs.zip

English

Customer View Model

ENG_CVM_1-103542-9_J.3d_stp.zip

English

Customer View Model

ENG_CVM_1-103542-9_J.2d_dxf.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English